

**APPLICATION DATA SHEET**

**Application Information**

Application Type:: Regular  
Subject Matter:: Utility  
Suggested Classification::  
Suggested Group Art Unit::  
Title:: A METHOD OF ASSEMBLING A  
SEMICONDUCTOR DEVICE PACKAGE  
Attorney Docket Number:: INF 4384  
Request for Early Publication?:: No  
Request for Non-Publication?:: No  
Suggested Drawing Figure::  
Total Drawing Sheets::  
Small Entity?:: No

**Applicant Information**

Applicant Authority Type:: Inventor  
Primary Citizenship Country:: Singapore  
Status:: Full Capacity  
Given Name:: Charles  
Family Name:: Lee  
City of Residence:: Singapore  
Country of Residence:: Singapore  
Street of Mailing Address:: Apt. Blk 110, Bukit Purmei Road  
#03-152  
City of Mailing Address:: Singapore  
Postal Code of Mailing Address:: 090110

Applicant Authority Type:: Inventor  
Primary Citizenship Country:: Austria  
Status:: Full Capacity  
Given Name:: Helmut  
Family Name:: Strack  
City of Residence:: Munich  
Country of Residence:: Germany  
Street of Mailing Address:: Speyererstrasse 6,  
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**Correspondence Information**

Correspondence Customer Number:: 000321

**Representative Information**

Representative Customer Number:: 000321

**Foreign Priority Information**

Country::	Application number::	Filing Date::	Priority Claimed::
PCT	PCT/SG99/00050	05/31/1999	Yes

**Assignee Information**

Assignee Name:: Infineon Technologies AG